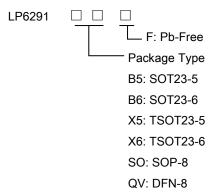


High Slew Rate Rail-to-Rail Single Operational Amplifiers with OTP

General Description

LP6291 is The rail-to-rail one channel operational amplifier with wide supply range from 6V to 18V. It provides 0.5V beyond the supply rails of common mode input range and capability of rail-to-rail output swing as well. This enables the amplifier to offer maximum dynamic range at any supply voltage among many applications. A 20MHz gain bandwidth product allows LP6291 to perform more stable than other devices in Internet applications. With features of 40V/µs high slew rate and 200ns of fast settling time, as well as 100mA (sink and source) of high output driving LP6291 is ideal for the the capability, requirements of flat panel Thin Film Transistor Crystal Displays (TFT-LCD) panel grayscale reference buffers application. Due to insensitive to power supply variation, LP6291 offers flexibility of use in multitude applications such as battery power, portable devices and anywhere low power consumption concerned. With standard operational amplifier pin assignment, the LP6291 is offered in a space saving 6-Pin SOT-26 package and specified over the -40°C to +85°C temperature

Order Information



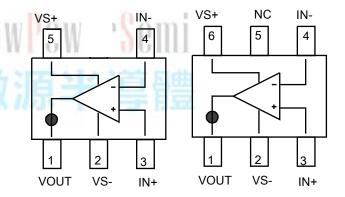
Applications

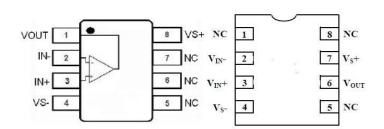
- TFT-LCD Reference Driver, ADC/DAC Buffer, Active Filter
- ♦ Office Automation, Wireless LANs, Portable Electronics
- ♦ Personal Communication Devices
- ♦ Direct Access Arrangement, Electronic Notebook
- ♦ Personal Digital Assistant (PDA)
- ♦ Touch-Screen Display, Sampling ADC Amplifier

Features

- ◆ Wide supply voltage range 6V ~ 18V
- Input range 500mV beyond the rails
- Unity-gain stable
- Rail-to-rail output swing
- ◆ High slew rate 40V/µs
- ♦ GBWP 20MHz
- 30MHz -3dB Bandwidth
- ♦ Ultra-small Package SOT-25、TSOT25、SOT-26、TSOT-26 and TSSOP-8

Pin Configurations







Pin Description

Pin Name	Pin Function	
VOUT	Operational Amplifier Output.	
VS-	IC GROUND or Negative power supply.	
IN+	Operational Amplifier Non-Inverting Input.	
IN-	Operational Amplifier Inverting Input.	
VS+	Supply Voltage VCC can range from 6V to 18V.	

Absolute Maximum Ratings Note 1

\diamond	Supply Voltage VS+ to VS	18V
\$	Input Voltage	VS0.5V to VS+ +0.5V
	Maximum Continuous Output Current	100mA
	Maximum Die Temperature	125°C
	Storage Temperature	
	Operating Temperature Range (TJ)	
\diamond	Maximum Soldering Temperature (at leads, 10 sec)	260°C

Important Note:

All parameters having Min/Max specifications are guaranteed. Typical values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore: TJ = TC = TA

Electrical Characteristics

 $(V_{S+=} + 5V, V_{S-} = -5V, R_L = 10k\Omega \text{ and } C_L = 10pF \text{ to } 0V, T_A = 25^{\circ}C \text{ unless otherwise specified.})$

Parameter	Description	Cond	lition	Min	Тур	Max	Units
Input Chara	cteristics	Zili A	SIE MARS	ने साम			
Vos	Input Offset Voltage	VcM= 0V		RE	2	12	mV
TCVos	Average Offset Voltage	[1]	1145		5		μV/°C
lв	InputDrift Bias Current	VcM= 0V			2	50	nA
Rin	Input Impedance				1		GΩ
CIN	Input Capacitance				1.35		pF
CMIR	Common-Mode Input			-5.0		+5.5	V
CMRR	Common-ModeRange Rejection	for VIN from -5.5V to	5.5V	50	70		dB
Avol	Open-Loop Gain	0.5V ≦VOUT≦4.5V		75	90		dB
Output Cha	racteristics					•	•
VoL	Output Swing Low-	VS+=8V,VS-=-8V,IL=	VS+=8V,VS-=-8V,IL=-5mA		-7.92	-	V
Vон	Output Swing High	VS+=8V,VS-=-8V,IL:	=5mA	7.85	7.92		V
Isc	Short Circuit Current	(Note 1)			±350		mA
Іоит	Output Current				±100		mΑ
peak	Ipeak Current	VS+=14V, VS-=0V	Source Current: I load Vout to GND		450		mA
·		(Note 2)	Sink Current: I load Vout to VDD				
Power Supp	oly Performance						
PSRR	Power Supply Rejection Ratio	VS is moved from ±2.25V to ±7.75V		60	80		dB
İs	Supply Current	No Load			3		mA

Parameter	Description	Condition	Min	Тур	Max	Units		
Dynamic Performance								
SR	Slew Rate [2]	VS+=8V,VS-=-8V, -4.0V≦VOUT≦□ 4.0V, 20% to 80%	30	40		V/µs		
ts	Settling to +0.1% (AV = +1)	(AV = +1), Vo=2V Step		500		Ns		
BW	-3dB Bandwidth	R _L = 10kΩ, C _L =10pF		30		MHz		
GBWP	Gain-Bandwidth Product	R _L = 10kΩ, CL=10pF		20		MHz		
PM	Phase Margin	$R_L = 10k\Omega$, $CL = 10 pF$		50		Degree		
CS	Channel Separation	f = 1 MHz		75		s dB		
Temperature Performance								
Temp	Thermal Shutdown			150		°C		
1. Measured	over operating temperature rand	ie		ı				

Note 1: Short circuit current is tested with one output at a time.

Note 2: Ipeak current is for a 1µs pulsed current only, not to exceed thermal characteristics of package.

Typical Operating Characteristics

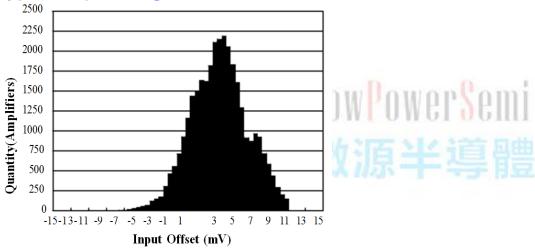


Figure (a) Input Offset Voltage Distribution

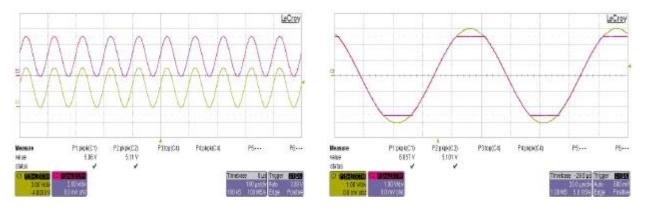


Figure (b) Rail to Rail Capability

Figure (c) Input Beyond the Rails Signal

^{2.} Slew rate is measured on rising and falling edges

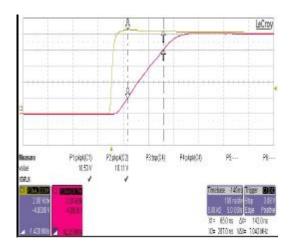


Figure (d) Large Signal Transient Response

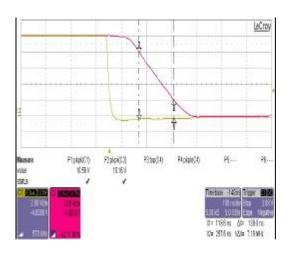


Figure (e) Large Signal Transient Response



APPLICATIONS INFORMATION

Product Description

The LP6291 rail-to-rail one channel amplifier is built on an advanced high voltage CMOS process. It's beyond rails input capability and full swing of output range makes itself an ideal amplifier for use in a wide range of general-purpose applications. The features of 40V/µs high slew rate, fast settling time, 30MHz of GBWP as well as high output driving capability have proven the LP6291 a good voltage reference buffer in TFT-LCD for grayscale reference applications. High phase margin and extremely low power consumption make the LP6291 ideal for connected in voltage follower mode for low power high drive applications.

Supply Voltage, Input Range and Output Swing

The LP6291 could be operated with a single nominal wide supply voltage ranging from 6V to 18V with stable performance over operating temperature of -40°C to +85°C. With 500mV greater than rail-to-rail input common mode voltage range and 70dB of Common Mode Rejection Ratio, the LP6291 allows a wide range sensing among many Applications without having a n y concerns over Exceeding the range and no compromise in accuracy. The output swings of the LP6291 typically extend to within 80mV of positive and negative supply rails with load currents of 5mA. The output voltage swing can be even closer to the supply rails by merely decreasing the load current. Figure 1 shows the input and output waveforms for The device in the unity-gain configuration. The amplifier is operated under $\pm 5V$ supply with a $10K\Omega$ load connected to GND. The input is a 10Vp-p sinusoid. An Approximately 9.985 Vp-p of output voltage swing can be easily achieved.

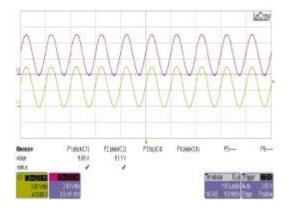


Figure 1. Operation with Rail-to-Rail Input and Output

Output Short Circuit Current Limit

A +/-350mA short circuit current will be limited by the LP6291 if the output is directly shorted to the positive or the negative supply. For an indefinitely output short circuit, the power dissipation could easily increase such that the device may be damaged. The internal metal interconnections are well designed to prevent the output continuous current from exceeding +/-100mA such that the maximum reliability can be well maintained.

Output Phase Reversal

The LP6291 is designed to prevent its output from being phase reversal as long as the input voltage is limited from VS- -0.5V to VS+ +0.5V. Figure 2 shows a photo of the device output with its input voltage driven beyond the supply rails. Although the phase of the device's output will not be reversed, the input's over-voltage should be avoided. An improper input voltage exceeds supply range by more than 0.6V may result in an over stress damage.

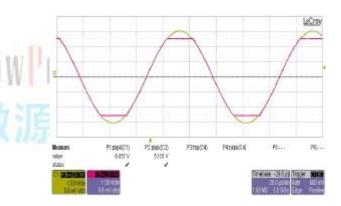


Figure 2. Operation with Beyond-the Rails Input

Power Dissipation

The LP6291 is designed for maximum output current capability. Even though momentary output shorted to ground causes little damage to device. For the high drive amplifier LP6291, it is possible To exceed the 'absolute-maximum junction temperature' under certain load current conditions. Therefore, it is important to calculate the maximum junction temperature for the application to determine if load conditions need to be modified for theamplifier to remain in the safe operating area.

The maximum power dissipation allowed in a package is determined according to:

$$P_{Dmax} = \frac{T_{Jmax} - T_{Amax}}{\Theta_{JAc}}$$

Where:

T_{Jmax} = Maximum Junction Temperature

Preliminary Datasheet LP6291

T_{Amax} = Maximum Ambient Temperature O_{JA} = Thermal Resistance of the Package

P_{Dmax} = Maximum Power Dissipation in the Package.

The maximum power dissipation actually produced by an IC is the total quiescent supply current times the total power supply voltage, plus the power in the IC due to the loads, or:

 $P_{Dmax} = \sum_{i} [VS * I_{Smax} + (VS + - VO) * I_{L}]$ When sourcing, and $P_{Dmax} = \sum_{i} [VS * I_{Smax} + (VO - VS -) * I_{L}]$ When sinking. Where: i = 1 to 1

VS = Total Supply Voltage

Ismax = Maximum Supply Current Per Amplifier **VO** = Maximum Output Voltage of the Application

IL= Load current

 $R_L = Load Resistance = (VS + - VO)/I_L = (VO - VS -)/I_L$

A calculation for R_L to prevent device from overheat can be easily solved by setting the two PDmax equations equal to each other.

Driving Capacitive Loads

The LP6291 is designed to drive a wide range of capacitive loads. In addition, the output current handling capability of the device allows for good slewing characteristics even with large capacitive loads. The combination of these features make the LP6291 ideally for applications such as TFT LCD panel grayscale reference voltage buffers, ADC input amplifiers, etc.

As load capacitance increases, however, the -3dB bandwidth of the device will decrease and the peaking Depending on the application, it must be necessary to reduce peaking and to improve device stability. To improve device stability, a small v al u e of series resistor (usually between 5Ω and 50Ω) must be placed in series with the output. The advantage is that it improves the settling and

overshooting performance with very large capacitive loads. Figure 3. shows the typical application configuration.

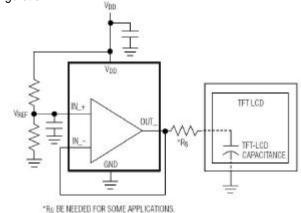


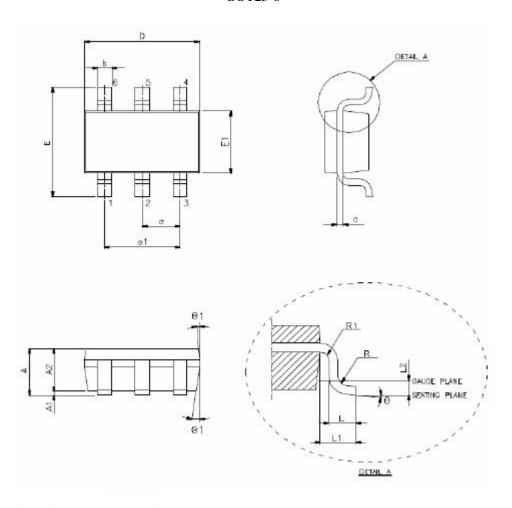
Figure 3. Typical Application Configuration.

Power Supply Bypassing and Printed Circuit **Board Layout**

With high phase margin, the LP6291 performs stable gain at high frequency. Like any highfrequency device, good layout of the printed circuit board usually comes with optimum performance. Ground plane construction is highly recommended, lead lengths should be as short as possible and the power supply pins must be well bypassed to reduce the risk of oscillation. For normal single supply operation, where the VS- pin is connected to ground, a 0.1 µF ceramic capacitor should be placed from VS+ pin to VS- pin as a bypassing capacitor. A 4.7μF tantalum capacitor should then be connected in parallel, placed in the region of the amplifier. One 4.7µF capacitor may be used for multiple devices. This same capacitor combination should be placed at each supply pin to ground if split supplies are to be used.

Packaging Information

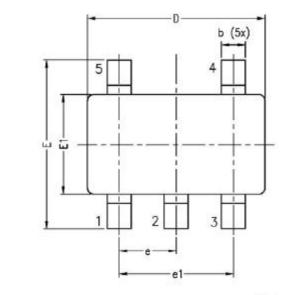
SOT23-6

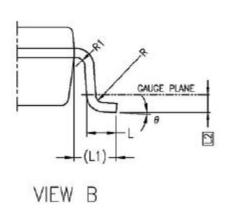


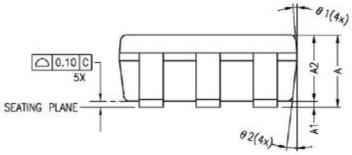
VARIATION(ALL DIMENSIONS SHOWN IN MM)

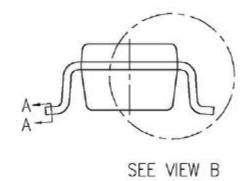
SYMBOL	MIN.	NOM.	MAX.
Α	33	2	1.45
A1	- <u></u>		0.15
A2	0.90	1.15	1.30
Ь	0.30	-	0.50
С	80.0	-	0.22
D	1	2.90 BSC.	
E		2.80 BSC.	
E1		1.60 BSC.	
e		0.95 BSC	
e1		1.90 BSC.	
L	0.30	0.45	0.60
L1		0.60 REF.	
L2		0.25 BSC	
R	0.10		-
R1	0.10		0.25
0	0.	4'	8,
01	5'	10"	15*

SOT23-5





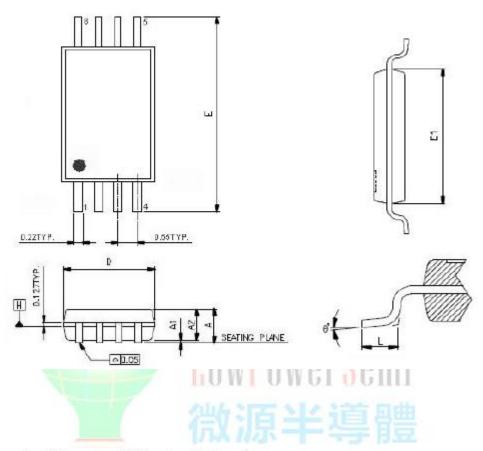




VARIATION(ALL DIMENSIONS SHOWN IN MM)

SYMBOL	MIN.	NOM.	MAX.
A	77		1.45
A1		[=]	0.15
A2	0.90	1.15	1,30
Ь	0.30		0.50
C	80.0	+	0.22
D		2.90 BSC.	
E	1	2.80 BSC.	
E1	1,60 BSC.		
е	1	0.95 BSC	
e1		1,90 BSC.	
L	0.30	0.45	0.60
L1	i i	0.60 REF.	
L2		0.25 BSC.	
R	0.10	- 122/2	370
R1	0.10		0.25
9	0.	4'	₿*
61	5'	10"	15*

TSSOP-8

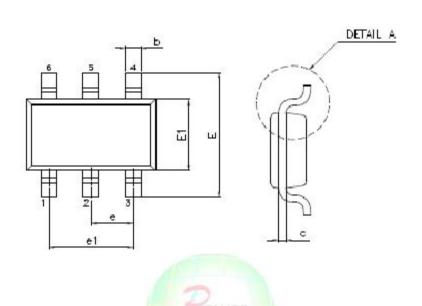


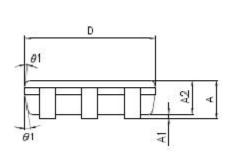
SYMBOLS	MIN.	NOM.	MAX.
A	-	<u></u>	1.20
A1	0.05	72	0.15
A2	0.96	1.01	1.06
D	2.90	3.00	3.10
E		6.40 BSC	
E1	4.30	4.40	4.50
L	0.45	0.60	0.75
θ,	0	97 -	8

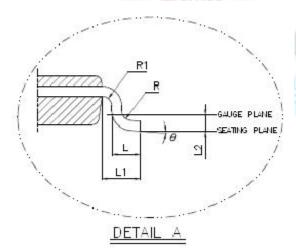
UNIT: MM



TSOT23-6







VARIATION(ALL DIMENSIONS SHOWN IN MM)

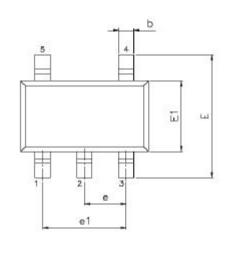
SYMBOL	OMIN	NOM.	MAX.		
A	0.750	_	0.800		
A1	0.000	_	0.050		
A2	0.700	0.750	0.775		
ь	0.350	_	0.500		
С	0.100	_	0.200		
D	2.800	2.900	3.000		
E	2.600	2.800	3.000		
E1	1.500	1.600	1.700		
е		0.950 BSC			
e 1		1.900 BSC			
L	0.370	0.450	0.600		
L1		0.600 REF			
L2	0.250 BSC				
R	0.100	_	_		
R1	0.100	-	0.250		
θ	ò	4"	8"		
<i>0</i> 1	4"	10"	12"		

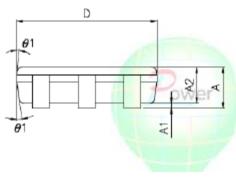
NOTE :

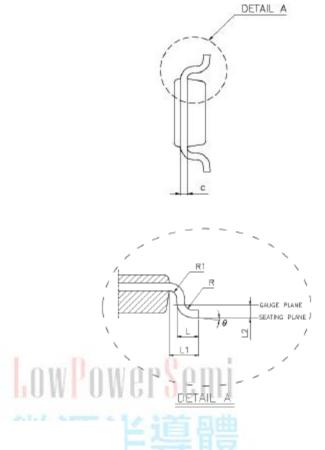
JEDEC OUTLINE : N/A.



TSOT23-5







SYMBOL	MIN.	NOM.	MAX.
А	0.750	-	0.800
A1	0.000	-	0.050
A2	0.700	0.750	0.775
b	0.350	-	0.500
С	0.100	-	0.200
D	2.800	2.900	3.000
Е	2.600	2.800	3.000
E1	1.500	1.600	1.700
е		0.950 BSC	
e1	1.900 BSC		
L	0.370	0.450	0.600
L1		0.600 REF	
L2	0.250 BSC		
R	0.100	-	-
R1	0.100	-	0.250
θ	0°	4°	8°
θ1	4°	10°	12°

单击下面可查看定价,库存,交付和生命周期等信息

>>LOW POWER(微源半导体)